



2016 Asia-Pacific Workshop on Fundamentals and Applications of Advanced Semiconductor Devices

Conference website: <http://www.ieice.org/~sdm/jpn/awad2016/index.html>

July 4 – 6, 2016

Hakodate Kokusai Hotel, Hakodate, Japan

Venue website: http://www.hakodate-kokusai.jp/index_en.php

2016 Asia-Pacific Workshop on Fundamentals and Applications of Advanced Semiconductor Devices will be held at the Hakodate Kokusai Hotel, Hakodate, Japan, from July 4th (Mon.) to July 6th (Wed.), 2016. This annual workshop has been held alternately in Japan and Korea since 1993, and the 2016 workshop will be the 24th in a series. The purposes of this workshop are to bring scientists and engineers together, actively engaged in advanced semiconductor devices and materials, and to discuss the present and future device processing and related technologies. The workshop will cover the entire field of semiconductor devices and materials, from fundamental physics to recent improvements in device performance and processing technology. Topics to be discussed will include, but not necessarily be limited to, the following areas:

- Advanced integration technologies
- ULSI process and technologies
- High-speed devices and circuits
- High power devices
- Wide bandgap materials and devices
- Novel devices and circuits
- Semiconductor devices applications
- MOS/bipolar devices and technologies
- Compound semiconductor materials and devices
- Microwave/Millimeter-wave devices and circuits
- TFT materials, devices and circuits
- Quantum effect/single electron devices
- Characterization and simulation
- Sensors and displays

Sponsored by

The Institute of Electronics, Information and Communication Engineers (IEICE) of Japan

In Cooperation with The Institute of Electronics and Information Engineers (IEIE) of Korea

Paper submission

Abstract deadline: ~~April 8th (Fri.)~~, April 22nd (Fri.), 2016

Prospective authors should send the paper submission form (template is available for download at the conference website) with paper title, author's name(s), affiliation(s), e-mail address, phone/fax number, and 100 words abstract by e-mail with "AWAD2016" + "your name" in the subject no later than **April 22nd (Fri.), 2016**, to:

awad2016@grp.tohoku.ac.jp

For any questions from Japan and other countries, ask:

Hiroya Ikeda (Shizuoka Univ.)
E-mail: ikeda.hiroya@shizuoka.ac.jp
Phone: +81-53-478-1317
Manabu Arai (New JRC)
E-mail: marai@njr.co.jp
Phone: +81-49-278-1441

For any questions from Korea, ask:

Hyuck-In Kwon (Chung-Ang Univ.)
E-mail: hyuckin@cau.ac.kr
Phone: +82-2-820-5293
Woo Young Choi (Sogang Univ.)
E-mail: wchoi@sogang.ac.kr
Phone: +82-2-705-8467

Technical Digest

The authors of the accepted abstracts will be asked to submit camera-ready manuscripts (2 - 6 pages including figures) for the technical digest which will be distributed to participants at the workshop. The details will directly be notified to the authors of accepted papers. The deadline of the camera-ready manuscript is May 25th (Wed.), 2016. The template for camera-ready manuscript will be available for download at the conference website.

Special issues in IEICE Transaction on Electronics (IEICE-C) / Journal of Semiconductor Science and Technology (JSTS)

Authors are encouraged to submit their extended manuscript to the special issue either in IEICE Transactions on Electronics (IEICE-C) or Journal of Semiconductor Technology and Science (JSTS). The submitted papers will be peer-reviewed and upon acceptance published in May 2017 (IEICE-C) or April 2017 (JSTS). Detail information will be accounted at the workshop and the conference website.

Venue & Accommodation

For detailed information, visit the conference website: <http://www.ieice.org/~sdm/jpn/awad2016/index.html>

Language

The official language of the workshop is English.

Registration

	Regular	Student
Early-registration Fee (JPY)	30,000	10,000
On-site Registration Fee (JPY)	35,000	13,000

* Early-registration deadline is June 3rd (Fri.), 2016.

* Registration form and payment information for the Early-registration will be available at the conference website.

* On-site registration payments can be received via either credit card or cash (Japanese currency only).

* Banquet fee is included in the registration fee.

Banquet

Banquet will be scheduled in the evening on Tuesday, July 5th, 2016.

Important Dates

~~April 8th (Fri.),~~ **April 22nd (Fri.), 2016: Abstract Submission Deadline**

May 25th (Wed.), 2016: Camera-ready Manuscript Submission Deadline

Workshop Co-chairs

Tatsuya Kunikiyo (Renesas), Ho-Young Cha (Hongik Univ.)

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